

26/pats
JC20 Rec'd PCT/PTO 26 SEP 2009

SPECIFICATION

PHOTODIODE ARRAY AND PRODUCTION METHOD THEREOF,
AND RADIATION DETECTORTechnical Field

5 [0001] The present invention relates to a photodiode array and production method thereof, and to a radiation detector.

Background Art

10 [0002] The photodiode arrays of this type conventionally known include back-illuminated photodiode arrays of a type in which light is incident through the opposite surface (back surface) to a surface where bump electrodes or the like are formed (e.g., reference is made to Patent Document 1). The photodiode array disclosed in this Patent Document 1 has photodiodes 140 of pn junctions made by forming p-layers 134 of prismatic shape in an n-type silicon substrate 133, as shown in Figs. 25 and 26. A scintillator 131 is bonded through a negative electrode film 136 to the back surface (the upper side in the drawing) opposite to the surface where the photodiodes 140 are formed (the lower side in the drawing). When light resulting from wavelength conversion in the scintillator 131 is incident into the photodiodes 140, each of the photodiodes 140 generates an electric current according to the incident light. The electric current generated in each photodiode 140 is outputted through positive electrode 135 formed on the front surface side, solder ball 139, and solder pad 138 provided on printed circuit board 137.

20 [0003] [Patent Document 1] Japanese Patent Application Laid-Open No. 7-333348

Disclosure of the Invention

[0004] Incidentally, for mounting of the aforementioned photodiode array, e.g., a photodiode array for CT, a flat collet or a pyramid collet can be used as a collet for holding a chip under suction. The flat collet is normally used for flip chip bonding. The CT photodiode array has a large chip area (e.g., the square shape of 20 mm on each side). Where the pyramid collet 161 used in an ordinary mounter is used as shown in Fig. 24B, chip 162 will warp due to clearance 163 between chip 162 and pyramid collet 161. For this reason, in the case where the pyramid collet 161 is used, the warpage could cause positional misalignment and degrade the mounting accuracy of chip 162. The flip chip bonding process requires application of heat and pressure, but the efficiency of thermal conduction is poor in use of the pyramid collet 161. The pressure applied could damage the edge of chip 162. From the above it follows that the pyramid collet 161 is not suitable for suction holding of a thin chip. Therefore, in the case of the flip chip bonding, as shown in Fig. 24A, flat collet 160 to achieve surface contact with the chip surface is used to hold the chip 162 under suction, and the heat and pressure from heater block 164 is applied to the chip 162.

[0005] However, the use of the flat collet 160 results in bringing the entire chip surface of the chip 162 into contact with the flat collet 160. If the entire chip surface to become the light-incident surface is in contact with the flat collet 160 to be exposed to pressure and heat, regions corresponding to impurity diffused layers forming the photodiodes, on the chip surface could suffer physical damage. The damage on the chip surface will pose problems of appearance failure

and characteristic degradation (increase in dark current and noise or the like).

[0006] The present invention has been accomplished in view of the above-described respects and an object of the invention is to provide a photodiode array and production method thereof capable of preventing the characteristic degradation while preventing the damage on the regions corresponding to the photodiodes during mounting, and to provide a radiation detector.

[0007] In order to achieve the above object, a photodiode array according to the present invention is a photodiode array comprising a semiconductor substrate, wherein a plurality of photodiodes are formed in array on an opposite surface side to an incident surface of light to be detected, in the semiconductor substrate, and wherein a resin film for transmitting the light to be detected is provided so as to cover at least regions corresponding to regions where the photodiodes are formed, on a side of the incident surface of the light to be detected, in the semiconductor substrate.

[0008] In the photodiode array according to the present invention, in the case of the flat collet being used during mounting, the resin film is interposed between the flat collet and the regions corresponding to the regions where the photodiodes are formed. For this reason, the regions corresponding to the regions where the photodiodes are formed are kept out of direct contact with the flat collet to be prevented from being damaged by pressure and heat. In consequence, it is feasible to effectively prevent the characteristic degradation due to noise, dark current, and so on.

[0009] Preferably, a plurality of depressions having a predetermined depth are formed in array on the opposite surface side to the incident surface of the light to be detected, in the semiconductor substrate, and each photodiode is formed in a bottom portion of the associated depression. In this case, the distance becomes shorter between the incident surface of the light to be detected and the photodiodes in the semiconductor substrate, and thus recombination of carriers is suppressed in migration of carriers generated with incidence of the light to be detected. This results in improving photodetecting sensitivity.

[0010] The resin film is provided so as to cover the entire incident surface of the light to be detected, in the semiconductor substrate. In this case, the resin film can be readily formed and this can facilitate production steps.

[0011] Preferably, the semiconductor substrate is provided with an impurity region between the photodiodes adjacent to each other, for separating the photodiodes from each other. In this case, the impurity region prevents occurrence of surface leak, and thus adjacent photodiodes can be electrically separated from each other with certainty.

[0012] Preferably, a high-impurity-concentration layer of the same conductivity type as the semiconductor substrate is formed on the incident surface side of the light to be detected, in the semiconductor substrate. In this case, carriers generated near the light-incident surface inside the semiconductor substrate efficiently migrate into each photodiode, without being trapped. This results in enhancing the photodetecting sensitivity.

[0013] A photodiode array production method according to the present

invention is a method of producing a photodiode array, the method comprising: a step of preparing a semiconductor substrate comprised of a semiconductor of a first conductivity type; a step of forming a plurality of impurity diffused layers of a second conductivity type on one surface side of the semiconductor substrate to form a plurality of photodiodes each comprised of the impurity diffused layer and the semiconductor substrate, in array; and a step of providing a resin film for transmitting light to which the photodiodes are sensitive, so as to cover at least regions corresponding to regions where the photodiodes are formed, on another surface of the semiconductor substrate.

[0014] The photodiode array production method according to the present invention permits us to obtain the photodiode array wherein the photodiodes are formed in array on one surface of the semiconductor substrate and wherein the resin film is provided at least in the regions corresponding to the regions where the photodiodes are formed, on the other surface.

[0015] Another photodiode array production method according to the present invention is a method of producing a photodiode array, the method comprising: a step of preparing a semiconductor substrate comprised of a semiconductor of a first conductivity type; a step of forming a plurality of depressions in array on one surface side of the semiconductor substrate; a step of forming a plurality of impurity diffused layers of a second conductivity type in bottom portions of the depressions to form a plurality of photodiodes each comprised of the impurity diffused layer and the semiconductor substrate, in array; and a step of providing a resin film for transmitting light to which the

photodiodes are sensitive, so as to cover at least regions corresponding to regions where the photodiodes are formed, on another surface of the semiconductor substrate.

5 [0016] The photodiode array production method according to the present invention permits us to obtain the photodiode array wherein the photodiodes are formed in array in the bottom portions of the depressions formed on one surface of the semiconductor substrate and wherein the resin film is provided at least in the regions corresponding to the regions where the photodiodes are formed, on the other surface.

10 [0017] Preferably, the method further comprises a step of forming a high-impurity-concentration layer of the first conductivity type on the other surface of the semiconductor substrate, prior to the step of providing the resin film. In this case, the high-impurity-concentration layer of the same conductivity type as the semiconductor substrate is
15 formed on the other surface of the semiconductor substrate. For this reason, carriers generated near the light-incident surface inside the semiconductor substrate efficiently migrate into each photodiode, without being trapped. This results in enhancing the photodetecting sensitivity.

20 [0018] Preferably, the method further comprises a step of providing an impurity region of the first conductivity type between the impurity diffused layers adjacent to each other. In this case, the method permits us to obtain the photodiode array wherein the photodiodes adjacent to each other are electrically separated from each other with certainty.

25 [0019] A radiation detector according to the present invention is a radiation detector comprising: the above-described photodiode array;

and a scintillator panel arranged opposite to the incident surface of the light to be detected, in the photodiode array, and arranged to emit light with incidence of radiation.

5 [0020] Another radiation detector according to the present invention is a radiation detector comprising: the photodiode array produced by the above-described photodiode array production method; and a scintillator panel arranged opposite to the surface where the resin film is provided in the photodiode array, and arranged to emit light with incidence of radiation.

10 [0021] Since each of these radiation detectors according to the present invention comprises the above-described photodiode array, it is feasible to effectively prevent the characteristic degradation due to noise, dark current, and so on.

Brief Description of the Drawings

15 [0022] Fig. 1 is a view showing a sectional configuration of a photodiode array according to the first embodiment.

[0023] Fig. 2 is a view for explaining the configuration of the photodiode array according to the first embodiment.

20 [0024] Fig. 3 is a view for explaining a production step of the photodiode array according to the first embodiment.

[0025] Fig. 4 is a view for explaining a production step of the photodiode array according to the first embodiment.

[0026] Fig. 5 is a view for explaining a production step of the photodiode array according to the first embodiment.

25 [0027] Fig. 6 is a view for explaining a production step of the photodiode array according to the first embodiment.

[0028] Fig. 7 is a view for explaining a production step of the photodiode array according to the first embodiment.

[0029] Fig. 8 is a view for explaining a production step of the photodiode array according to the first embodiment.

5 [0030] Fig. 9 is a view for explaining a production step of the photodiode array according to the first embodiment.

[0031] Fig. 10 is a view for explaining a production step of the photodiode array according to the first embodiment.

10 [0032] Fig. 11 is a view for explaining a production step of the photodiode array according to the first embodiment.

[0033] Fig. 12 is a view showing a sectional configuration of a modification example of the photodiode array according to the first embodiment.

15 [0034] Fig. 13 is a view showing a sectional configuration of a photodiode array according to the second embodiment.

[0035] Fig. 14 is a view for explaining the configuration of the photodiode array according to the second embodiment.

[0036] Fig. 15 is a view for explaining a production step of the photodiode array according to the second embodiment.

20 [0037] Fig. 16 is a view for explaining a production step of the photodiode array according to the second embodiment.

[0038] Fig. 17 is a view for explaining a production step of the photodiode array according to the second embodiment.

25 [0039] Fig. 18 is a view for explaining a production step of the photodiode array according to the second embodiment.

[0040] Fig. 19 is a view for explaining a production step of the

photodiode array according to the second embodiment.

[0041] Fig. 20 is a view for explaining a production step of the photodiode array according to the second embodiment.

5 [0042] Fig. 21 is a view for explaining a production step of the photodiode array according to the second embodiment.

[0043] Fig. 22 is a view showing a sectional configuration of a radiation detector according to the third embodiment.

[0044] Fig. 23 is a view showing a sectional configuration of a radiation detector according to the fourth embodiment.

10 [0045] Fig. 24A is a view schematically showing a state in which a flat collet holds a semiconductor chip under suction.

[0046] Fig. 24B is a view schematically showing a state in which a pyramid collet holds a semiconductor chip under suction.

15 [0047] Fig. 25 is a perspective view showing a photodiode array according to the conventional technology.

[0048] Fig. 26 is a schematic diagram showing a sectional configuration along direction XXVI-XXVI in Fig. 25.

Best Mode for Carrying out the Invention

20 [0049] The preferred embodiments of the photodiode array and production method thereof, and the radiation detector according to the present invention will be described below in detail with reference to the drawings. The same elements, or elements with the same functionality will be denoted by the same reference symbols in the description, without redundant description.

25 [0050] (First Embodiment)

Fig. 1 is a view showing a sectional configuration of photodiode

array 1 according to an embodiment of the present invention. In the description hereinafter, the incident surface of light L (the upper surface in Fig. 1) will be referred to as a back surface, and the opposite surface (the lower surface in Fig. 1) to it as a front surface. It is noted that the dimensions in each drawing below are altered as occasion may demand, for convenience' sake of illustration.

[0051] The photodiode array 1 has a plurality of photodiodes 4 comprised of pn junctions. The plurality of photodiodes 4 are two-dimensionally arranged in a vertically and horizontally regular array on the front surface side of the photodiode array 1. Each photodiode 4 functions as a pixel of photodiode array 1 and the photodiodes 4 as a whole constitute one photosensitive region.

[0052] The photodiode array 1 has an n-type (first conductivity type) silicon substrate 3. The thickness of the n-type silicon substrate 3 is approximately 30-300 μm (preferably, 100 μm). The impurity concentration in the n-type silicon substrate 3 is approximately 1×10^{12} - $10^{15}/\text{cm}^3$. P-type (second conductivity type) impurity diffused layers 5 are two-dimensionally arranged in a vertically and horizontally regular array on the front surface side of the n-type silicon substrate 3. The thickness of the p-type impurity diffused layers 5 is approximately 0.05-20 μm (preferably, 0.2 μm). The impurity concentration in the p-type impurity diffused layers 5 is approximately 1×10^{13} - $10^{20}/\text{cm}^3$. The pn junctions formed of the p-type impurity diffused layers 5 and the n-type silicon substrate 3 constitute the photodiodes 4. A silicon oxide film 22 is formed on the front surface of the n-type silicon substrate 3. A passivation film 2 is formed on this silicon oxide film 22. The

passivation film 2 is made, for example, of SiN or the like.

[0053] Electrode wirings 9 are formed corresponding to the respective p-type impurity diffused layers 5 (photodiodes 4), on the silicon oxide film 22. Each electrode wiring 9 is made of aluminum and has the thickness of about 1 μm . One end of each electrode wiring 9 is electrically connected through a contact hole formed in the silicon oxide film 22, to the corresponding p-type impurity diffused layer 5. The other end of each electrode wiring 9 is electrically connected through a contact hole formed in the passivation film 2, to a corresponding under bump metal (UBM) 11. A bump electrode 12 of solder is formed on each UBM 11. The UBM 11 and bump electrode 12 are electrically connected to each other.

[0054] The UBM 11 is preferably one achieving strong interface bonding to solder and being capable of preventing diffusion of a solder component into aluminum, and is often constructed in multilayer structure. An example of this multilayer structure is nickel (Ni)-gold (Au) by electroless plating. This structure is obtained by depositing a thick nickel plated layer (3-15 μm) on an aluminum-exposed region and depositing a thin gold plated layer (0.05-0.1 μm) thereon. The gold layer is provided for preventing oxidation of nickel. Other available structures include multilayer structures of titanium (Ti)-platinum (Pt)-gold (Au) and chromium (Cr)-gold (Au) formed by liftoff.

[0055] An accumulation layer 8 as a high-impurity-concentration layer is provided on the back surface side of the n-type silicon substrate 3. The accumulation layer 8 is formed in a substantially uniform depth across almost all the back surface. The accumulation layer 8 has the

same conductivity type as the n-type silicon substrate 3 and the impurity concentration thereof is higher than that of the n-type silicon substrate 3. The photodiode array 1 of the present embodiment has the accumulation layer 8, but the photodiode array has the photodetecting sensitivity at a practically acceptable level, without provision of the accumulation layer 8.

[0056] An AR film 24 is formed on the accumulation layer 8, in order to cover and protect the accumulation layer 8 and to suppress reflection of light L. The AR film 24 is made, for example, of SiO_2 and has the thickness of about 0.01 to several μm . The AR film 24 may be formed in a multilayer or complex structure with SiN or with an optical film capable of preventing reflection at a desired wavelength, in addition to SiO_2 .

[0057] On the front surface side of the n-type silicon substrate 3, a region where each p-type impurity diffused layer 5 exists is a region where a photodiode 4 is formed (hereinafter referred to as a "formed region"), and the region except for the formed regions constitutes a region where the photodiodes are not formed. A resin film 6 is provided so as to cover at least regions corresponding to the formed regions of the respective photodiodes 4 (the regions will be referred to hereinafter as "corresponding regions"), on AR film 24. The resin film 6 is made of a resin material that transmits light to be detected (light to which the photodiodes 4 are sensitive) L. In the present embodiment, the resin film 6 covers the entire AR film 24.

[0058] An n^+ -type impurity region 7 is provided between adjacent p-type impurity diffused layers 5, i.e., between adjacent photodiodes 4 in

the n-type silicon substrate 3. The thickness of the n⁺-type impurity region 7 is approximately 0.1-several ten μm . The n⁺-type impurity region 7 functions as a separating layer for electrically separating adjacent photodiodes 4 (p-type impurity diffused layers 5) from each other. This can securely electrically separate adjacent photodiodes 4 from each other and reduce crosstalk between photodiodes 4. The photodiode array 1 in the present embodiment, without the n⁺-type impurity region 7, possesses the photodetecting characteristics at a practically acceptable level.

[0059] The photodiode array 1 is of extremely thin plate shape, as shown in Fig. 2. The width W1 of photodiode array 1 is approximately 22.4 mm, and the thickness D of photodiode array 1 is approximately 0.3 mm. The photodiode array 1 has a number of aforementioned photodiodes 4 (e.g., a two-dimensional array of 256 (16×16) photodiodes). The pitch W2 between adjacent photodiodes 4 (pixels) is approximately 1.4 mm. The photodiode array 1 is a chip of a large area (e.g., 22.4 mm × 22.4 mm). The top illustration in Fig. 2 is one for showing how thin the photodiode array 1 is, and the details of the photodiode array 1 are illustrated in enlarged views.

[0060] In the photodiode array 1, when light L is incident on the back surface, the incident light L passes through the resin layer 6 and the accumulation layer 8 to reach the pn junctions. Then each photodiode 4 generates carriers according to the incident light. At this time, the accumulation layer 8 prevents the carriers generated near the light-incident surface (back surface) inside the n-type silicon substrate 3 from being trapped at the light-incident surface and the interface to the AR

film 24. This permits the carriers to efficiently migrate to the pn junctions and thus enhances the photodetecting sensitivity of the photodiode array 1. A photocurrent caused by generated carriers is extracted through electrode wiring 9 and UBM 11 connected to each p-type impurity diffused layer 5, and from bump electrode 12. The incident light is detected based on the output from the bump electrode 12.

[0061] In the present embodiment, as described above, the resin film 6 capable of covering the corresponding regions of the respective photodiodes 4 is provided on the incident surface side of the light L (i.e., the back surface side) in the photodiode array 1. In the case where the flip chip bonding is carried out with the photodiode array 1 being held in suction by the flat collet, the resin film 6 is brought into contact with the flat collet to be located between the flat collet and the corresponding regions of the respective photodiodes 4. In this configuration, the corresponding regions of the respective photodiodes 4 are protected by the resin film 6 so as to be kept out of direct contact with the flat collet. Therefore, the corresponding regions of the respective photodiodes 4 get rid of direct stress due to pressure and direct stress due to heat, so that the accumulation layer 8 in the corresponding regions is prevented from suffering physical damage. The photodiodes 4 are thus free of the dark current and noise caused by crystal defects or the like due to such damage. In consequence, the photodiode array 1 is able to perform photodetection with high accuracy (at high S/N ratios).

[0062] As described later, the resin film 6 can function as a cushion layer capable of protecting the corresponding regions of the respective

photodiodes 4. This also permits the resin film 6 to absorb physical impact in holding the photodiode array in suction on the flat collet.

[0063] In cases except for the flip chip bonding, e.g., in a case where the photodiode array 1 is integrated with a scintillator to be used as a CT sensor, as described later, the scintillator is kept out of direct contact with the corresponding regions, and it is thus feasible to avoid damage during mounting of the scintillator.

[0064] Incidentally, the necessary condition for resin film 6 is that the resin film 6 is provided in the range where it can cover at least the entire corresponding regions of the photodiodes 4. As long as this condition is met, the resin film 6 of a single layer may be provided so as to cover the entire corresponding regions of the photodiodes 4. In another configuration, a plurality of resin films 6 are provided corresponding to the corresponding regions of the photodiodes 4 and missing portions 6a without the resin film 6 may exist in the region not corresponding to the formed regions of the photodiodes 4 (the region not corresponding will be referred to hereinafter as a "noncorresponding region") (cf. Fig. 12). It is, however, preferable to provide the single-layer resin film 6 so as to cover the entire corresponding regions of the photodiodes 4, in terms of simplifying the production steps (which will be detailed later).

[0065] The resin film 6 is placed as a protecting film for the entire corresponding regions of the photodiodes 4, on the incident surface side. Therefore, the resin film 6 is made of a light transmitting resin that is capable of transmitting light detected by the photodiode array 4 (light to be detected, e.g., fluorescence generated by scintillator panel 31 as described later) and optically transparent to the light to be detected; for

example, such resins as epoxy resin, polyimide resin, acrylate resin, silicone resin, fluororesin, and urethane resin. The resin layer 6 is in direct contact with the flat collet during the flip chip bonding to be exposed to pressure and heat. Therefore, the resin layer 6 is preferably made of a material capable of protecting the corresponding regions of the respective photodiodes 4 from the pressure and heat. In this case, for example, the resin preferably has the coefficient of thermal expansion of approximately 1×10^{-6} - $1 \times 10^{-4}/^{\circ}\text{C}$, the elastic modulus of approximately 10-12000 kg/cm², and the thermal conductivity of 0.2-1.85 W/m²°C. The resin layer 6 is preferably formed in a thickness in which impurity ions are kept from diffusing into the photodiodes 4 with application of heat and in which at least light from scintillator panel 31 described later can be absorbed thereby (approximately 1-50 μm (preferably, 10 μm)).

[0066] Next, a production method of the photodiode array 1 according to the present embodiment will be described below on the basis of Figs. 3 to 11.

[0067] The first step is to prepare an n-type silicon substrate 3 having the thickness of about 150-500 μm (preferably, 350 μm), as shown in Fig. 3. Next, a silicon oxide film (SiO₂) 20 is formed on the front surface and on the back surface of the n-type silicon substrate 3 (cf. Fig. 4).

[0068] Next, the silicon oxide film 20 formed on the front surface of the n-type silicon substrate 3 is patterned with a predetermined photomask to form openings at intended positions for formation of the n⁺-type impurity regions 7. Then the n-type silicon substrate 3 is doped with

phosphorus through the openings formed in the silicon oxide film 20, to provide the n^+ -type impurity regions 7 in the n-type silicon substrate 3. In the present embodiment, the n^+ -type impurity region 7 is also formed on the back surface side of the n-type silicon substrate 3. This step (impurity region forming step) may be omitted if the n^+ -type impurity regions 7 are not provided. Subsequently, a silicon oxide film 21 is again formed on the front surface and on the back surface of the n-type silicon substrate 3 (cf. Fig. 5). This silicon oxide film 21 is used as a mask in the subsequent step of forming the p-type impurity diffused layers 5.

[0069] Next, the silicon oxide film 21 formed on the front surface of the n-type silicon substrate 3 is patterned with a predetermined photomask to form openings at intended positions for formation of the respective p-type impurity diffused layers 5. The substrate is doped with boron through the openings formed in the silicon oxide film 21, to form the p-type impurity diffused layers 5 in two-dimensional arrangement of a vertical and horizontal array. This results in forming photodiodes 4 of pn junctions between each p-type impurity diffused layer 5 and n-type silicon substrate 3 in two-dimensional arrangement of a vertical and horizontal array. Each photodiode 4 becomes a portion corresponding to a pixel. Subsequently, a silicon oxide film 22 is again formed on the front surface side of the substrate (cf. Fig. 6).

[0070] Next, the back surface of the n-type silicon substrate 3 is polished up to a predetermined thickness (about 30-300 μm) to obtain the n-type silicon substrate 3 in thin shape (thin plate). Then an n-type ion species (e.g., phosphorus or arsenic) is allowed to diffuse from the

back surface of the n-type silicon substrate 3 into the depth of about 0.05 to several ten μm , thereby forming the aforementioned accumulation layer 8 with the impurity concentration higher than that of the n-type silicon substrate 3. Furthermore, thermal oxidation is carried out to form the AR film 24 on the accumulation layer 8 (cf. Fig. 7).

[0071] Next, contact holes extending to the respective p-type impurity diffused layers 5 are formed in the formed regions of the respective photodiodes 4 and in the silicon oxide film 22 by the photoetching technology. Subsequently, an aluminum metal film is formed on the silicon oxide film 22 by evaporation, and thereafter it is patterned with a predetermined photomask to form electrode wirings 9 (cf. Fig. 8).

[0072] Next, a resin such as epoxy resin, polyimide resin, acrylate resin, silicone resin, fluororesin, or urethane resin as a material of resin film 6 is applied onto the AR film 24, it is spread over the entire surface by spin coating, screen printing, or the like, and it is cured to provide the resin film 6 (cf. Fig. 9). As this resin film 6 is provided, it protects the corresponding regions of the respective photodiodes 4. In the case where the missing portions 6a are formed in the resin film 6, the applied resin is removed from the regions of the missing portions 6a. In this case, the resin film also protects the corresponding regions of the respective photodiodes 4.

[0073] After the formation of resin film 6, an SiN film 25 to become the passivation film 2 is formed on the silicon oxide film 22 so as to cover the electrode wirings 9. The SiN film 25 can be formed by sputtering, plasma CVD, or the like. The passivation film 2 may be

one selected from the insulating films of SiO₂, PSG, BPSG, etc., polyimide resin, acrylate resin, epoxy resin, fluororesin, composite films and multilayer films thereof, and so on. The step of forming the passivation film 2 may be carried out before the formation of the resin film 6.

[0074] Next, contact holes are formed at predetermined positions in the SiN film 25 to make electrode extracting portions (cf. Fig. 10). Furthermore, the bump electrodes 12 are to be formed. Where the bump electrodes 12 are of solder, since the solder has poor wettability to aluminum, UBM 11 for intervention between each electrode extracting portion and bump electrode 12 is formed on each electrode extracting portion. Then the bump electrode 12 is formed over each UBM 11 (cf. Fig. 11).

[0075] Through the above steps, the production method permits us to produce the photodiode array 1 capable of performing photodetection with high accuracy, without occurrence of noise due to damage in mounting.

[0076] The bump electrodes 12 can be made by placing solder on the predetermined UBM 11 by the solder ball mounting method or printing method and reflowing the solder. The bump electrodes 12 are not limited to the solder bumps, but may be gold bumps, nickel bumps, or copper bumps, or may be electroconductive resin bumps containing such metal as an electroconductive filler. The drawings show only the extraction of the anode electrodes, and the cathode (substrate) electrodes can also be similarly extracted from the n⁺-type impurity regions 7 (though not shown) in the same manner as the anode electrodes. The

drawings show the case where the bump electrodes 12 of the anode electrodes are formed in the areas of the n^+ -type impurity regions 7, but the bump electrodes 12 of the anode electrodes may be formed in the areas of the p-type impurity diffused layers 5.

5 [0077] (Second Embodiment)

Next, the second embodiment of the photodiode array and production method thereof will be described.

10 [0078] The present embodiment is directed to a photodiode array 41 having an n-type silicon substrate 43 in which depressions 45 are formed on the opposite surface side (front surface side) to the incident surface of light L, as shown in Fig. 13. Since this photodiode array 41 has common portions to the photodiode array 1, the description below will be given with focus on the differences between them, while omitting or simplifying the description of the common portions.

15 [0079] In the photodiode array 41, a plurality of depressions 45 are formed in two-dimensional arrangement of a vertically and horizontally regular array on the front surface side of the n-type silicon substrate 43. Each depression 45 is made by recessing a predetermined region of the n-type silicon substrate 43 so as to make it thinner than the region
20 around it, and the depressions 45 are formed at arrangement intervals of about 1.4-1.5 mm. The aforementioned photodiodes 4 are formed in respective bottom portions 45a of the depressions 45, thereby constituting the photodiode array 41 in which the photodiodes 4 are two-dimensionally arranged in array.

25 [0080] Each depression 45 is formed with a rectangular opening, for example, in the size of about 1 mm \times 1 mm in the front surface of the n-

type silicon substrate 43 so that the aperture size gradually decreases from the opening toward the bottom portion 45a (i.e., from the front surface side toward the back surface side). In this configuration, each depression 45 has a slope side surface 45b. The depth from the front surface of the n-type silicon substrate 43 to the bottom portion 45a is, for example, about 50 μm .

[0081] Electrode wirings 9 are formed along side faces 45b and on the silicon oxide film 22. One end of each electrode wiring 9 is electrically connected through a contact hole formed in the silicon oxide film 22, to the corresponding p-type impurity diffused layer 5. The other end of each electrode wiring 9 is electrically connected through a contact hole formed in the passivation film 2, to the corresponding UBM 11. An n^+ -type impurity region 7 is provided between adjacent photodiodes 4.

[0082] The accumulation layer 8 is formed on the entire back surface side of the n-type silicon substrate 3. The AR film 24 is formed on the accumulation layer 8. This accumulation layer 8 and the AR film 24 are similar to those in the aforementioned photodiode array 1. The aforementioned resin film 6 is provided in the corresponding region of each photodiode 4 on the AR film 24. The resin film 6 is also similar to that in the aforementioned photodiode array 1.

[0083] The photodiode array 41 is of extremely thin plate shape as shown in Fig. 14. The width W1 of the photodiode array 41 is approximately 22.4 mm, and the thickness D of photodiode array 41 is 150-300 μm . The photodiode array 41 has a number of such photodiodes 4 (e.g., two-dimensional arrangement of 256 (16 \times 16)

photodiodes). The pitch W2 between adjacent photodiodes 4 is approximately 1.4 mm. The photodiode array 41 is a chip of a large area (e.g., 22.4 mm × 22.4 mm). The top illustration in Fig. 14 is one showing how thin the photodiode array 41 is, and the details of the photodiode array 41 are illustrated in enlarged views.

[0084] In the photodiode array 41 constructed as described above, when light L is incident on the back surface, just as in the case of the photodiode array 1, the incident light L passes through the resin film 6 and the accumulation layer 8 to reach the pn junctions. Each photodiode 4 generates carriers according to the incident light. Since each pn junction is provided in the bottom portion 45a of depression 45, the distance is shorter between the back surface of the n-type silicon substrate 43 and the pn junction (e.g., approximately 10-100 μm). Therefore, the photodiode array 41 is configured to prevent a situation in which the carriers generated with incidence of light L annihilate through recombination in the process of migration. In consequence, the photodiode array 41 is able to maintain high detection sensitivity.

[0085] The accumulation layer 8 permits the carriers generated near the light-incident surface (back surface) inside the n-type silicon substrate 3 to efficiently migrate to the pn junctions, without recombination. This permits the photodiode array 41 to have higher photodetecting sensitivity (though the photodiode array 41 of the present embodiment has the detection sensitivity at a practically acceptable level, without provision of the accumulation layer 8).

[0086] A photocurrent caused by generated carriers is extracted through electrode wiring 9 and UBM 11 connected to each p-type impurity

diffused layer 5, and from bump electrode 12. The incident light is detected based on the output from bump electrode 12. This is much the same as in the case of the photodiode array 1.

[0087] As described above, the photodiode array 41 of the present embodiment is also provided with the resin film 6 capable of covering the corresponding regions of the respective photodiodes 4, on the incident surface side of the light L (i.e., the back surface side) in the photodiode array 41 as the photodiode array 1 was. In the case where the flip chip bonding is carried out with the photodiode array 41 being held in suction with the flat collet, the resin film 6 is brought into contact with the flat collet to be located between the flat collet and the corresponding regions of the respective photodiodes 4. In this configuration, the resin film 6 protects the corresponding regions of the respective photodiodes 4, so that the corresponding regions are kept out of direct contact with the flat collet. Therefore, the corresponding regions of the photodiodes 4 get rid of direct stress due to pressure and direct stress due to heat, so that the accumulation layer 8 in the corresponding regions is prevented from suffering physical damage. In the photodiodes 4 there is neither dark current nor noise caused by crystal defects or the like due to such damage. In consequence, the photodiode array 41 is able to perform photodetection with high accuracy (at high S/N ratios).

[0088] In cases except for the flip chip bonding, for example, in a case where the photodiode array 41 is integrated with a scintillator to be used as a CT sensor, as described later, the scintillator is kept out of direct contact with the corresponding regions and it is thus feasible to avoid

damage during mounting of the scintillator.

[0089] Next, a production method of the photodiode array 41 according to the present embodiment will be described on the basis of Figs. 3 to 6 and Figs. 15 to 21.

5 [0090] First, the steps described with Figs. 3 to 6 are executed in the same manner as in the case of the photodiode array 1. Next, the back surface of the n-type silicon substrate 3 is polished to make the n-type silicon substrate 3 thinner (into a thin plate) before the thickness of the n-type silicon substrate 3 becomes a predetermined thickness.
10 Subsequently, a silicon nitride film (SiN) 26 is formed on the front surface and on the back surface of the n-type silicon substrate 3 by LP-CVD (or plasma CVD), and thereafter the silicon oxide film 22 and silicon nitride film 26 on the front surface side are patterned with a predetermined photomask to form openings at intended positions for
15 formation of the respective depressions 45 (cf. Fig. 15).

[0091] Next, the p-type impurity diffused layer 5 and n-type silicon substrate 3 are removed by alkali etching to form a depression 45 so as to leave a frame peripheral part 5a of p-type impurity diffused layer 5, for each target of a region where the p-type impurity diffused layer 5 is
20 formed, in the front surface of the n-type silicon substrate 3. This results in obtaining an n-type silicon substrate 43. At this time, the frame peripheral part 5a is formed as a region resulting from diffusion with a p-type impurity, in the edge part of the opening of each depression 45. Each depression 45 comes to have a side face 45b and
25 a bottom portion 45a. The frame peripheral part 5a is not always essential. When the frame peripheral part 5a is formed, it provides the

effect of preventing noise and dark current due to damage in the edge part formed by etching for formation of the depressions 45. Figs. 13, 14, and 23 show the example without formation of the frame peripheral part 5a.

5 [0092] Subsequently, the bottom portion 45a of each depression 45 thus formed is doped with boron or the like. This results in forming a p-type impurity diffused layer 5b in the bottom portion 45a of each depression 45, and the photodiodes 4 comprised of pn junctions of such
10 p-type impurity diffused layers 5b and n-type silicon substrate 43 are formed in two-dimensional arrangement of a vertical and horizontal array. Then a silicon oxide film 22 is formed on the regions not covered by the silicon nitride film 26 formed on the front surface (cf. Fig. 16). At this time, though not shown, the silicon oxide film is also formed on the silicon nitride film 26 formed on the back surface.

15 [0093] Next, the silicon nitride film 26 formed on the back surface of n-type silicon substrate 43 is removed and thereafter the accumulation layer 8 with the impurity concentration higher than that of the n-type silicon substrate 43 is formed by ion implantation with an n-type ion species (e.g., phosphorus or arsenic). Furthermore, thermal oxidation
20 is conducted to form the AR film 24 on the accumulation layer 8. Thereafter, the silicon nitride film 26 formed on the front surface of the n-type silicon substrate 43 is removed (cf. Fig. 17).

[0094] Then, in the formed region of each photodiode 4 a contact hole extending up to each p-type impurity diffused layer 5b is formed in the
25 silicon oxide film 22 on the front surface side by photoetching technology. Subsequently, an aluminum metal film is formed on the

silicon oxide film 22 by evaporation and thereafter patterned with a predetermined photomask to form the electrode wirings 9 (cf. Fig. 18).

[0095] Next, the resin film 6 is provided on the AR film 24 in the same manner as in the first embodiment (cf. Fig. 19).

5 [0096] After the formation of resin film 6, an SiN film 25 to become the passivation film 2 is formed on the silicon oxide film 22 so as to cover the electrode wirings 9. The SiN film 25 can be formed by sputtering, plasma CVD, or the like. Subsequently, contact holes are formed at positions corresponding to the respective electrode wirings 9
10 in the SiN film 25 (cf. Fig. 20). Subsequently, the UBM 11 electrically connected with each electrode wiring 9 through the contact hole is formed by electroless plating or the like in the same manner as in the first embodiment. Then the bump electrode 12 is formed over each UBM 11 (cf. Fig. 21).

15 [0097] Through the above steps, the production method permits us to produce the photodiode array 41 capable of performing photodetection with high accuracy, without occurrence of the noise and dark current due to damage during mounting. The drawings show only the extraction of the anode electrodes, but the cathode (substrate) electrodes
20 can also be extracted from the n^+ -type impurity regions 7 (though not shown) in the same manner as the anode electrodes.

[0098] (Third Embodiment)

Next, a radiation detector according to the third embodiment will be described.

25 [0099] Fig. 22 is a view showing a sectional configuration of radiation detector 50 according to the present embodiment. This radiation

detector 50 has a scintillator panel 31 arranged to emit light with incidence of radiation, and the aforementioned photodiode array 1. The scintillator panel 31 emits light generated with incident radiation, from its light exit surface 31a. The scintillator panel 31 is arranged
5 opposite to the light-incident surface of photodiode array 1, i.e., opposite to the surface with the resin film 6 in the photodiode array 1. When the light emerging from the light exit surface 31a of scintillator panel 31 is incident on the light-incident surface, the photodiode array 1 converts the incident light into electric signals.

10 [0100] The scintillator panel 31 is mounted on the back surface side (incident surface side) of the photodiode array 1. Since the photodiode array 1 is provided with the aforementioned resin film 6, the back surface of the scintillator panel 31, i.e., the light exit surface 31a is kept out of direct contact with the corresponding regions of the photodiodes
15 4. The space between the light exit surface 31a of the scintillator panel 31 and the resin film 6 is filled with an optical resin 35 having a refractive index set so as to sufficiently transmit the light. This optical resin 35 allows the light from the scintillator panel 31 to efficiently enter the photodiode array 1. This optical resin 35 can be selected
20 from epoxy resin, acrylic resin, urethane resin, silicone resin, fluoro-resin, etc. with the property of transmitting the light from the scintillator panel 31, or may be one of composite materials of these resins.

25 [0101] In an operation of bonding the photodiode array 1 onto an unrepresented mounting wiring board, the flat collet holds the photodiode array 1 under suction. However, since the photodiode

array 1 is provided with the aforementioned resin film 6, the sticking surface of the flat collet is kept out of direct contact with the corresponding regions of the respective photodiodes 4. When the scintillator panel 31 is mounted, its light exit surface 31a is not in direct contact with the corresponding regions of the photodiodes 4, either. Therefore, the radiation detector 50 having such photodiode array 1 and scintillator panel 31 is able to prevent occurrence of noise, dark current, etc. due to damage of the corresponding regions in the mounting. In consequence, the radiation detector 50 is able to accurately perform photodetection and, in turn, to accurately perform radiation detection.

[0102] (Fourth Embodiment)

Next, a radiation detector according to the fourth embodiment will be described.

[0103] Fig. 23 is a view showing a sectional configuration of radiation detector 55 according to the present embodiment. This radiation detector 55 has a scintillator panel 31, and the aforementioned photodiode array 41. The scintillator panel 31 is arranged opposite to the light-incident surface of photodiode array 41, i.e., opposite to the surface where the resin film 6 is provided in the photodiode array 41.

[0104] The scintillator panel 31 is mounted on the back surface side (incident surface side) of the photodiode array 41. Since the photodiode array 41 is provided with the aforementioned resin film 6, the back surface of the scintillator panel 31, i.e., the light exit surface 31a is kept out of direct contact with the corresponding regions of the photodiodes 4. The clearance between the light exit surface 31a of the scintillator panel 31 and the resin film 6 is filled with an optical resin 35

having a refractive index set in consideration of such characteristics as to sufficiently transmit light. This optical resin 35 allows the light from the scintillator panel 31 to efficiently enter the photodiode array 41.

5 [0105] In an operation of bonding the photodiode array 41 to an unrepresented mounting wiring board, the flat collet holds the photodiode array 41 under suction. However, since the photodiode array 41 is provided with the aforementioned resin film 6, the sticking surface of the flat collet is not in direct contact with the corresponding regions of the respective photodiodes 4. When the scintillator panel 31 is mounted, its light exit surface 31a is also kept out of direct contact with the corresponding regions of the photodiodes 4. Therefore, the radiation detector 55 having such photodiode array 41 and scintillator panel 31 is able to prevent occurrence of noise, dark current, etc. due to damage of the corresponding regions in the mounting. In consequence, the radiation detector 55 is able to accurately perform photodetection and, in turn, to accurately perform radiation detection.

10 [0106] The invention accomplished by the Inventors was specifically described above on the basis of the embodiments thereof, but the present invention is by no means intended to be limited to the above embodiments. For example, the resin film 6 may be provided directly on the n-type silicon substrate 3, 43, or may be provided through a structure such as the AR film 24 thereon.

Industrial Applicability

20 [0107] The present invention is applicable to X-ray CT scanners and radiographic image taking systems.